

EAST-10053910 bonding pad.wsp:1

FileViewEditToolsWindowHelp

Pending

Active

Failed

Saved

L1: (1) 10/053910

L2: (165) ((w1r\$3 near bond\$3) near12 crack) and (reflect\$3 near3 (layer film)) ((w1r\$3 n

L3: (5) "1186320" "08213422" "64081236" "11145288"

L4: (3) "2001015671"

L5: (2) 8184143 pn

(8916) ((multilevel\$2 multi\$3 adj level\$2 multilayer\$2 multi\$3 adj layer\$2) adj (interconn

(278544) ((multilevel\$2 multi\$3 adj level\$2 multilayer\$2 multi\$3 adj layer\$2))

(3450401) interconnect\$4 (inter adj connect\$4) wiring metal metalization metallization

(3446454) interconnect\$4 (inter adj connect\$4) wiring metal meta??ization

(2047046) pad contact

(7344860) (open\$5 via hole aperture trench groove well cavity)

(253431) (pad contact) near2 ((open\$5 via hole aperture trench groove well cavity))

(31765) (interconnect\$4 (inter adj connect\$4) wiring metal meta??ization) near9 ((pad c

(1889) (257758).CCLS

(613) ((interconnect\$4 (inter adj connect\$4) wiring metal meta??ization) near8 ((pad con

(6110) ((interconnect\$4 (inter adj connect\$4) wiring metal meta??ization) near8 ((pad co

(172) ((interconnect\$4 (inter adj connect\$4) wiring metal meta??ization) near9 ((pad cor

(111) ((interconnect\$4 (inter adj connect\$4) wiring metal meta??ization) near9 ((pad cor

(10) (((interconnect\$4 (inter adj connect\$4) wiring metal meta??ization) near8 ((pad con

(329) (((interconnect\$4 (inter adj connect\$4) wiring metal meta??ization) near9 ((pad con

(279801) (insulat\$5 dielectric) near layer

(15085) (insulat\$5 dielectric) near layer)

(58) (((interconnect\$4 (inter adj connect\$4) wiring metal meta??ization) near8 ((pad con

(1106) (insulat\$5 dielectric) near layer)

DBs

USPAT:US:POFUB:EPO:JPO:DERWENT:IBM:TDS

Plurals

Default operator: OR

Highlight all hit terms initially

6184143.pn

July 2004

DBs

USPAT:US:POFUB:EPO:JPO:DERWENT:IBM:TDS

Plurals

Default operator: OR

Highlight all hit terms initially

6184143.pn

July 2004

	U	Inventor	Document ID	Issue D Pa	Title	Current O	Current X Ref	Retrieval Cl	S	C	P	2	3	4	5	Image Doc. D P
1	<input checked="" type="checkbox"/>	NOGUCHI, J et al	JP 11145288 A	200405/80	Insulating film structure for copper wiring in semicond.				<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 6184143
2	<input checked="" type="checkbox"/>	Ohashi, Naofumi	US 6184143 B	200102/80	Semiconductor integrated circuit device and fabricati	438/697	257/E21.58		<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 6184143

Ready

MSH